

# RELIABILITY MONITOR

STRESS: WRITE CYCLE STRESS

CONDITIONS: 85 C, 7.0 VOLTS

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1620	D1	SEP '01	27862	0111 NSEB	DJ051232AAI	SOIC	50	50	0
DS1620	D1	DEC '01	28596	0112 CPS (ChipPac, China)	DH052443AAD	SOIC	50	50	0

# RELIABILITY MONITOR

STRESS: ULTRASOUND

CONDITIONS: J-STD-020

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1100	A3	OCT '01	28532	0126	ATP (Amkor, PI)	DK114601ADC	SOIC		4	0
DS1100	A3	JAN '02	28611	0132	ATP (Amkor, PI)	DK115002AKC	SOIC		4	0
DS1233	A5-5	APR '01	26868	0101	Fastech	DA048537AF	SOT223		4	0
DS1233	A5-5	JUL '01	27349	0110	Carsem	DM048543AA	SOT223		4	0
DS1233	A5-5	OCT '01	28003	0128	Fastech	DA102602AC	SOT223		4	0
DS1620	D1	SEP '01	27856	0111	NSEB	DJ051232AAI	SOIC		4	0
DS1620	D1	DEC '01	28590	0112	CPS (ChipPac, China)	DH052443AAD	SOIC		4	0
DS1803	A2	FEB '01	26606	0105	OSEP	DE047362AAB	SOIC		4	0
DS1803	A2	MAY '01	26990	0115	Carsem	DM052456AC	SOIC		4	0
DS1803	A2	AUG '01	27560	0119	OSEP	DE105519ACA	SOIC		4	0
DS1803	A2	NOV '01	28555	0143	ATP (Amkor, PI)	DK122629AAB	SOIC		4	0
DS2108	B7	MAY '01	26983	0111	ATP (Amkor, PI)	DK101048AAC	SOIC		4	0
DS2118M	C1	MAR '02	28816	0143	ATK (Amkor, K)	DN120700ABB	SSOP		4	0
DS2154	A2	DEC '01	28580	0126	ATP (Amkor, PI)	DK119150AAA	LQFP		4	0
DS2175	D1	APR '01	26880	0050	ATP (Amkor, PI)	DK036683ABD	SOIC		4	0
DS21Q43	A3-	SEP '01	27877	0047	Stats	DC036714AAD	LQFP		4	0
DS21S07	C1-	FEB '02	28805	0112	Carsem	DM048483AC	TSSOP		4	0
DS80CH11	A4	JUN '01	27104	0108	ATK (Amkor, K)	DN034351AA	LQFP		4	0
DS80CH11	A4	SEP '01	27864	0110	Stats	DC037148AA	LQFP		4	0
DS80CH11	A4	DEC '01	28598	0113	ATK (Amkor, K)	DN036754AA	LQFP		4	0
DS87C520	A15-	FEB '02	28777	0206	ATP (Amkor, PI)	DK101111AAA	PLCC		4	0

# RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: -40 TO 85C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1230	A1-Y	JAN '02	28621	0201 Fastech	304930	Module w/SMT	300	100	1
DS12887	A2-	OCT '01	28013	0137 Fastech	303363	Module w/Bent Fra	300	100	0
DS12887	A2-	JAN '02	28607	0203 Dallas	305911	Module w/Bent Fra	300	100	0
DS1644	B2	FEB '01	26628	0051 Fastech	300700	Power Cap	300	77	0
DS1992	E7-F	DEC '01	28569	0201 Dallas	304746-1	iButton F50 w/Bum	300	77	0
DS1992	E7-F	MAR '02	28774	0209 Fastech	320503-1	iButton F50 w/Bum	300	77	0

# RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: -55C TO 125C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1100	A3	OCT '01	28536	0126	ATP (Amkor, PI)	DK114601ADC	SOIC	300	40	0
DS1100	A3	OCT '01	28536	0126	ATP (Amkor, PI)	DK114601ADC	SOIC	1000	40	0
DS1100	A3	JAN '02	28615	0132	ATP (Amkor, PI)	DK115002AKC	SOIC	300	40	0
DS1100	A3	JAN '02	28615	0132	ATP (Amkor, PI)	DK115002AKC	SOIC	1000	40	0
DS1233	A5-5	APR '01	26872	0101	Fastech	DA048537AF	SOT223	700	40	10
DS1233	A5-5	APR '01	26872	0101	Fastech	DA048537AF	SOT223	1000	29	0
DS1233	A5-5	JUL '01	27353	0110	Carsem	DM048543AA	SOT223	700	40	0
DS1233	A5-5	JUL '01	27353	0110	Carsem	DM048543AA	SOT223	1000	26	0
DS1233	A5-5	OCT '01	28007	0128	Fastech	DA102602AC	SOT223	700	40	0
DS1233	A5-5	OCT '01	28007	0128	Fastech	DA102602AC	SOT223	1000	40	0
DS1302	A4	SEP '01	27795	0133	ATP (Amkor, PI)	DK101008AD	PDIP	300	40	0
DS1302	A4	SEP '01	27795	0133	ATP (Amkor, PI)	DK101008AD	PDIP	1000	40	0
DS1302	A4	MAR '02	28813	0204	CPS (ChipPac, China)	DE214012AA	PDIP	300	45	0
DS1302	A4	MAR '02	28813	0204	CPS (ChipPac, China)	DE214012AA	PDIP	1000	45	0
DS1620	D1	SEP '01	27860	0111	NSEB	DJ051232AAI	SOIC	300	40	0
DS1620	D1	SEP '01	27860	0111	NSEB	DJ051232AAI	SOIC	1000	40	0
DS1620	D1	DEC '01	28594	0112	CPS (ChipPac, China)	DH052443AAD	SOIC	300	40	0
DS1620	D1	DEC '01	28594	0112	CPS (ChipPac, China)	DH052443AAD	SOIC	1000	40	0
DS1803	A2	FEB '01	26611	0105	OSEP	DE047362AAB	SOIC	300	40	0
DS1803	A2	FEB '01	26611	0105	OSEP	DE047362AAB	SOIC	1000	34	0
DS1803	A2	MAY '01	26994	0115	Carsem	DM052456AC	SOIC	300	40	0
DS1803	A2	MAY '01	26994	0115	Carsem	DM052456AC	SOIC	1000	31	0

# RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: -55C TO 125C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1803	A2	AUG '01	27564	0119	OSEP	DE105519ACA	SOIC	300	40	0
DS1803	A2	AUG '01	27564	0119	OSEP	DE105519ACA	SOIC	1000	40	0
DS1803	A2	NOV '01	28559	0143	ATP (Amkor, PI)	DK122629AAB	SOIC	300	40	0
DS1803	A2	NOV '01	28559	0143	ATP (Amkor, PI)	DK122629AAB	SOIC	1000	40	0
DS2108	B7	MAY '01	26987	0111	ATP (Amkor, PI)	DK101048AAC	SOIC	300	40	1
DS2108	B7	MAY '01	26987	0111	ATP (Amkor, PI)	DK101048AAC	SOIC	1000	39	0
DS2118M	C1	MAR '02	28820	0143	ATK (Amkor, K)	DN120700ABB	SSOP	300	80	0
DS2118M	C1	MAR '02	28820	0143	ATK (Amkor, K)	DN120700ABB	SSOP	1000	80	0
DS2154	A2	DEC '01	28584	0126	ATP (Amkor, PI)	DK119150AAA	LQFP	300	72	0
DS2154	A2	DEC '01	28584	0126	ATP (Amkor, PI)	DK119150AAA	LQFP	1000	72	0
DS2175	D1	APR '01	26884	0050	ATP (Amkor, PI)	DK036683ABD	SOIC	300	40	0
DS2175	D1	APR '01	26884	0050	ATP (Amkor, PI)	DK036683ABD	SOIC	1000	40	0
DS21Q43	A3-	SEP '01	27881	0047	Stats	DC036714AAD	LQFP	300	77	0
DS21Q43	A3-	SEP '01	27881	0047	Stats	DC036714AAD	LQFP	1000	76	0
DS21S07	C1-	FEB '02	28809	0112	Carsem	DM048483AC	TSSOP	300	45	0
DS2401	C2	MAR '02	28836	0208	Carsem	DM218006AA	SOT23	300	45	1
DS2401	C2	MAR '02	28836	0208	Carsem	DM218006AA	SOT23	1000	44	0
DS80CH11	A4	JUN '01	27108	0108	ATK (Amkor, K)	DN034351AA	LQFP	300	70	0
DS80CH11	A4	JUN '01	27108	0108	ATK (Amkor, K)	DN034351AA	LQFP	1000	70	0
DS80CH11	A4	SEP '01	27868	0110	Stats	DC037148AA	LQFP	300	70	0
DS80CH11	A4	SEP '01	27868	0110	Stats	DC037148AA	LQFP	1000	68	0
DS80CH11	A4	DEC '01	28602	0113	ATK (Amkor, K)	DN036754AA	LQFP	300	70	0

# RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: -55C TO 125C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS80CH11	A4	DEC '01	28602	0113 ATK (Amkor, K)	DN036754AA	LQFP	1000	69	0
DS87C520	A15-	FEB '02	28781	0206 ATP (Amkor, PI)	DK101111AAA	PLCC	300	50	0
DS87C520	A15-	FEB '02	28781	0206 ATP (Amkor, PI)	DK101111AAA	PLCC	1000	50	0

# RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: 0C TO 70C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1643	C1	NOV '01	28565	0151 Dallas	304797	Module w/Hi Densit	300	77	0
DS1643	C1	NOV '01	28565	0151 Dallas	304797	Module w/Hi Densit	1000	77	0

# RELIABILITY MONITOR

STRESS: STORAGE LIFE

CONDITIONS: 150C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1620	D1	SEP '01	27863	0111 NSEB	DJ051232AAI	SOIC	336	50	0
DS1620	D1	SEP '01	27863	0111 NSEB	DJ051232AAI	SOIC	1000	50	0
DS1620	D1	DEC '01	28597	0112 CPS (ChipPac, China)	DH052443AAD	SOIC	336	50	0
DS1620	D1	DEC '01	28597	0112 CPS (ChipPac, China)	DH052443AAD	SOIC	1000	50	0
DS87C520	A15-	FEB '02	28783	0206 ATP (Amkor, PI)	DK101111AAA	PLCC	336	50	0
DS87C520	A15-	FEB '02	28783	0206 ATP (Amkor, PI)	DK101111AAA	PLCC	1000	50	0

# RELIABILITY MONITOR

STRESS: STORAGE LIFE

CONDITIONS: 70 C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1643	C1	NOV '01	28564	0151	Dallas	304797	Module w/Hi Densit	336	77	0
DS1643	C1	NOV '01	28564	0151	Dallas	304797	Module w/Hi Densit	1000	77	0
DS1644	B2	FEB '01	26627	0051	Fastech	300700	Power Cap	336	71	1
DS1644	B2	FEB '01	26627	0051	Fastech	300700	Power Cap	1000	69	0
DS1992	E7-F	DEC '01	28568	0201	Dallas	304746-1	iButton F50 w/Bum	336	77	0
DS1992	E7-F	DEC '01	28568	0201	Dallas	304746-1	iButton F50 w/Bum	1000	77	0
DS1992	E7-F	MAR '02	28773	0209	Fastech	320503-1	iButton F50 w/Bum	336	77	0
DS1992	E7-F	MAR '02	28773	0209	Fastech	320503-1	iButton F50 w/Bum	1000	77	0

# RELIABILITY MONITOR

STRESS: STORAGE LIFE

CONDITIONS: 85 C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1230	A1-Y	JAN '02	28620	0201 Fastech	304930	Module w/SMT	48	200	0

# RELIABILITY MONITOR

STRESS: SOLDERABILITY

CONDITIONS: JESD22-B102

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1230	A1-Y	JAN '02	28618	0201 Fastech	304930	Module w/SMT		3	0
DS12887	A2-	OCT '01	28010	0137 Fastech	303363	Module w/Bent Fra		3	0
DS12887	A2-	JAN '02	28605	0203 Dallas	305911	Module w/Bent Fra		3	0

# RELIABILITY MONITOR

STRESS: SOLDERABILITY

CONDITIONS: MIL-STD-883-2003

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT QTY FAIL
DS1643	C1	NOV '01	28562	0151 Dallas	304797	Module w/Hi Densit	3 0

# RELIABILITY MONITOR

STRESS: PRECONDITION U/S

CONDITIONS: J-STD-020

PRODUCT	REV	MONITOR		DATE	ASSEMBLY	LOT NO.	PACKAGE	READ	
		DATE	JOB NO					CODE	FACILITY
DS1100	A3	OCT '01	28534	0126	ATP (Amkor, PI)	DK114601ADC	SOIC	4	0
DS1100	A3	JAN '02	28613	0132	ATP (Amkor, PI)	DK115002AKC	SOIC	4	0
DS1233	A5-5	JUL '01	27351	0110	Carsem	DM048543AA	SOT223	4	0
DS1233	A5-5	OCT '01	28005	0128	Fastech	DA102602AC	SOT223	4	0
DS1620	D1	SEP '01	27858	0111	NSEB	DJ051232AAI	SOIC	4	0
DS1620	D1	DEC '01	28592	0112	CPS (ChipPac, China)	DH052443AAD	SOIC	4	0
DS1803	A2	FEB '01	26608	0105	OSEP	DE047362AAB	SOIC	4	0
DS1803	A2	MAY '01	26992	0115	Carsem	DM052456AC	SOIC	4	3
DS1803	A2	AUG '01	27562	0119	OSEP	DE105519ACA	SOIC	4	1
DS1803	A2	NOV '01	28557	0143	ATP (Amkor, PI)	DK122629AAB	SOIC	4	0
DS2108	B7	MAY '01	26985	0111	ATP (Amkor, PI)	DK101048AAC	SOIC	4	0
DS2118M	C1	MAR '02	28818	0143	ATK (Amkor, K)	DN120700ABB	SSOP	4	0
DS2154	A2	DEC '01	28582	0126	ATP (Amkor, PI)	DK119150AAA	LQFP	4	0
DS21Q43	A3-	SEP '01	27879	0047	Stats	DC036714AAD	LQFP	4	0
DS21S07	C1-	FEB '02	28807	0112	Carsem	DM048483AC	TSSOP	4	0
DS80CH11	A4	JUN '01	27106	0108	ATK (Amkor, K)	DN034351AA	LQFP	4	0
DS80CH11	A4	SEP '01	27866	0110	Stats	DC037148AA	LQFP	4	0
DS80CH11	A4	DEC '01	28600	0113	ATK (Amkor, K)	DN036754AA	LQFP	4	0
DS87C520	A15-	FEB '02	28779	0206	ATP (Amkor, PI)	DK101111AAA	PLCC	4	0

# RELIABILITY MONITOR

STRESS: PHYSICAL DIMENSIONS

CONDITIONS: JESD22-B100

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1230	A1-Y	JAN '02	28619	0201 Fastech	304930	Module w/SMT		6	0
DS12887	A2-	OCT '01	28011	0137 Fastech	303363	Module w/Bent Fra		6	0
DS12887	A2-	JAN '02	28606	0203 Dallas	305911	Module w/Bent Fra		6	0

# RELIABILITY MONITOR

STRESS: PHYSICAL DIMENSIONS

CONDITIONS: MIL-STD-883-2016

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT QTY FAIL
DS1643	C1	NOV '01	28563	0151 Dallas	304797	Module w/Hi Densit	6 0

# RELIABILITY MONITOR

STRESS: MOISTURE SOAK

CONDITIONS: 60C/90% R.H.

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1230	A1-Y	JAN '02	28622	0201 Fastech	304930	Module w/SMT	288	100	0
DS1230	A1-Y	JAN '02	28622	0201 Fastech	304930	Module w/SMT	960	100	0
DS1643	C1	NOV '01	28566	0151 Dallas	304797	Module w/Hi Densit	288	77	0
DS1643	C1	NOV '01	28566	0151 Dallas	304797	Module w/Hi Densit	960	77	0
DS1644	B2	FEB '01	26629	0051 Fastech	300700	Power Cap	288	77	0
DS1644	B2	FEB '01	26629	0051 Fastech	300700	Power Cap	960	72	0
DS1992	E7-F	DEC '01	28570	0201 Dallas	304746-1	iButton F50 w/Bum	288	77	0
DS1992	E7-F	DEC '01	28570	0201 Dallas	304746-1	iButton F50 w/Bum	960	77	0
DS1992	E7-F	MAR '02	28775	0209 Fastech	320503-1	iButton F50 w/Bum	288	77	0
DS1992	E7-F	MAR '02	28775	0209 Fastech	320503-1	iButton F50 w/Bum	960	77	0

# RELIABILITY MONITOR

STRESS: INFANT LIFE

CONDITIONS: 85 C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS12887	A2-	OCT '01	28012	0137 Fastech	303363	Module w/Bent Fra	48	200	0

# RELIABILITY MONITOR

STRESS: HAST, NO BIAS

CONDITIONS: 130C, 85% R.H.

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS2154	A2	DEC '01	28585	0126	ATP (Amkor, PI)	DK119150AAA	LQFP	200	72	0
DS21Q43	A3-	SEP '01	27883	0047	Stats	DC036714AAD	LQFP	100	40	0
DS80CH11	A4	JUN '01	27110	0108	ATK (Amkor, K)	DN034351AA	LQFP	100	40	1
DS80CH11	A4	SEP '01	27870	0110	Stats	DC037148AA	LQFP	100	40	0
DS80CH11	A4	DEC '01	28604	0113	ATK (Amkor, K)	DN036754AA	LQFP	100	44	0

# RELIABILITY MONITOR

STRESS: HAST

CONDITIONS: 130C, 85%R.H.,5.5V

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1233	A5-5	APR '01	26873	0101 Fastech	DA048537AF	SOT223	100	77	0
DS1233	A5-5	JUL '01	27354	0110 Carsem	DM048543AA	SOT223	100	77	0
DS1233	A5-5	OCT '01	28008	0128 Fastech	DA102602AC	SOT223	100	77	0
DS2401	C2	MAR '02	28837	0208 Carsem	DM218006AA	SOT23	96	77	0
DS87C520	A15-	FEB '02	28782	0206 ATP (Amkor, PI)	DK101111AAA	PLCC	96	58	1

# RELIABILITY MONITOR

STRESS: CONVECTION REFLOW

CONDITIONS: 220C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1644	B2	FEB '01	26625	0051 Fastech	300700	Power Cap	2	225	0
DS87C520	A15-	FEB '02	28778	0206 ATP (Amkor, PI)	DK101111AAA	PLCC	3	239	0

# RELIABILITY MONITOR

STRESS: CONVECTION REFLOW

CONDITIONS: 235C

PRODUCT	REV	MONITOR		DATE	ASSEMBLY	LOT NO.	PACKAGE	READ		
		DATE	JOB NO					CODE	FACILITY	POINT
DS1100	A3	OCT '01	28533	0126	ATP (Amkor, PI)	DK114601ADC	SOIC	3	238	0
DS1100	A3	JAN '02	28612	0132	ATP (Amkor, PI)	DK115002AKC	SOIC	3	238	0
DS1233	A5-5	APR '01	26869	0101	Fastech	DA048537AF	SOT223	3	238	0
DS1233	A5-5	JUL '01	27350	0110	Carsem	DM048543AA	SOT223	3	241	0
DS1233	A5-5	OCT '01	28004	0128	Fastech	DA102602AC	SOT223	3	241	1
DS1620	D1	SEP '01	27857	0111	NSEB	DJ051232AAI	SOIC	3	244	0
DS1620	D1	DEC '01	28591	0112	CPS (ChipPac, China)	DH052443AAD	SOIC	3	244	0
DS1803	A2	FEB '01	26607	0105	OSEP	DE047362AAB	SOIC	3	238	0
DS1803	A2	MAY '01	26991	0115	Carsem	DM052456AC	SOIC	3	238	0
DS1803	A2	AUG '01	27561	0119	OSEP	DE105519ACA	SOIC	3	241	0
DS1803	A2	NOV '01	28556	0143	ATP (Amkor, PI)	DK122629AAB	SOIC	3	241	0
DS2108	B7	MAY '01	26984	0111	ATP (Amkor, PI)	DK101048AAC	SOIC	3	238	0
DS2118M	C1	MAR '02	28817	0143	ATK (Amkor, K)	DN120700ABB	SSOP	3	238	4
DS2154	A2	DEC '01	28581	0126	ATP (Amkor, PI)	DK119150AAA	LQFP	3	238	1
DS2175	D1	APR '01	26881	0050	ATP (Amkor, PI)	DK036683ABD	SOIC	3	238	0
DS21Q43	A3-	SEP '01	27878	0047	Stats	DC036714AAD	LQFP	3	241	0
DS21S07	C1-	FEB '02	28806	0112	Carsem	DM048483AC	TSSOP	3	243	0
DS80CH11	A4	JUN '01	27105	0108	ATK (Amkor, K)	DN034351AA	LQFP	3	239	0
DS80CH11	A4	SEP '01	27865	0110	Stats	DC037148AA	LQFP	3	242	0
DS80CH11	A4	DEC '01	28599	0113	ATK (Amkor, K)	DN036754AA	LQFP	3	244	1

# RELIABILITY MONITOR

STRESS: BIASED MOISTURE

CONDITIONS: 85/85, 5.5 VOLTS

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS12887	A2-	OCT '01	28014	0137	Fastech	303363	Module w/Bent Fra	274	99	0
DS12887	A2-	OCT '01	28014	0137	Fastech	303363	Module w/Bent Fra	959	99	0
DS12887	A2-	JAN '02	28608	0203	Dallas	305911	Module w/Bent Fra	274	100	0
DS12887	A2-	JAN '02	28608	0203	Dallas	305911	Module w/Bent Fra	959	100	0
DS1302	A4	SEP '01	27796	0133	ATP (Amkor, PI)	DK101008AD	PDIP	274	77	1
DS1302	A4	SEP '01	27796	0133	ATP (Amkor, PI)	DK101008AD	PDIP	959	76	0
DS1302	A4	MAR '02	28814	0204	CPS (ChipPac, China)	DE214012AA	PDIP	274	77	0
DS1302	A4	MAR '02	28814	0204	CPS (ChipPac, China)	DE214012AA	PDIP	959	77	0
DS1620	D1	SEP '01	27861	0111	NSEB	DJ051232AAI	SOIC	274	70	0
DS1620	D1	SEP '01	27861	0111	NSEB	DJ051232AAI	SOIC	959	70	0
DS1620	D1	DEC '01	28595	0112	CPS (ChipPac, China)	DH052443AAD	SOIC	274	70	0
DS1620	D1	DEC '01	28595	0112	CPS (ChipPac, China)	DH052443AAD	SOIC	959	70	0
DS1803	A2	FEB '01	26612	0105	OSEP	DE047362AAB	SOIC	274	77	0
DS1803	A2	FEB '01	26612	0105	OSEP	DE047362AAB	SOIC	959	66	0
DS1803	A2	MAY '01	26995	0115	Carsem	DM052456AC	SOIC	274	77	0
DS1803	A2	MAY '01	26995	0115	Carsem	DM052456AC	SOIC	959	77	0
DS1803	A2	AUG '01	27565	0119	OSEP	DE105519ACA	SOIC	274	77	0
DS1803	A2	AUG '01	27565	0119	OSEP	DE105519ACA	SOIC	959	77	0
DS1803	A2	NOV '01	28560	0143	ATP (Amkor, PI)	DK122629AAB	SOIC	274	77	0
DS2108	B7	MAY '01	26988	0111	ATP (Amkor, PI)	DK101048AAC	SOIC	274	77	0
DS2108	B7	MAY '01	26988	0111	ATP (Amkor, PI)	DK101048AAC	SOIC	959	76	0
DS2175	D1	APR '01	26885	0050	ATP (Amkor, PI)	DK036683ABD	SOIC	274	77	0

## RELIABILITY MONITOR

STRESS: BIASED MOISTURE

CONDITIONS: 85/85, 5.5 VOLTS

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS2175	D1	APR '01	26885	0050	ATP (Amkor, PI)	DK036683ABD	SOIC	959	77	0
DS21Q43	A3-	SEP '01	27882	0047	Stats	DC036714AAD	LQFP	274	32	0
DS21Q43	A3-	SEP '01	27882	0047	Stats	DC036714AAD	LQFP	959	32	0
DS21S07	C1-	FEB '02	28810	0112	Carsem	DM048483AC	TSSOP	274	77	0
DS80CH11	A4	JUN '01	27109	0108	ATK (Amkor, K)	DN034351AA	LQFP	274	46	1
DS80CH11	A4	JUN '01	27109	0108	ATK (Amkor, K)	DN034351AA	LQFP	959	32	0
DS80CH11	A4	SEP '01	27869	0110	Stats	DC037148AA	LQFP	274	42	0
DS80CH11	A4	SEP '01	27869	0110	Stats	DC037148AA	LQFP	959	31	0
DS80CH11	A4	DEC '01	28603	0113	ATK (Amkor, K)	DN036754AA	LQFP	274	31	0
DS80CH11	A4	DEC '01	28603	0113	ATK (Amkor, K)	DN036754AA	LQFP	959	31	0

# RELIABILITY MONITOR

STRESS: AUTOCLAVE

CONDITIONS: 121C, 2 ATM STEAM, UNBIASED

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1100	A3	OCT '01	28538	0126	ATP (Amkor, PI)	DK114601ADC	SOIC	168	40	0
DS1100	A3	JAN '02	28617	0132	ATP (Amkor, PI)	DK115002AKC	SOIC	168	39	0
DS1233	A5-5	APR '01	26874	0101	Fastech	DA048537AF	SOT223	96	40	0
DS1233	A5-5	JUL '01	27355	0110	Carsem	DM048543AA	SOT223	96	40	0
DS1233	A5-5	OCT '01	28009	0128	Fastech	DA102602AC	SOT223	96	40	0
DS1302	A4	SEP '01	27797	0133	ATP (Amkor, PI)	DK101008AD	PDIP	96	40	0
DS1302	A4	MAR '02	28815	0204	CPS (ChipPac, China)	DE214012AA	PDIP	168	45	0
DS1803	A2	FEB '01	26613	0105	OSEP	DE047362AAB	SOIC	96	30	0
DS1803	A2	MAY '01	26996	0115	Carsem	DM052456AC	SOIC	96	37	0
DS1803	A2	AUG '01	27566	0119	OSEP	DE105519ACA	SOIC	96	40	0
DS1803	A2	NOV '01	28561	0143	ATP (Amkor, PI)	DK122629AAB	SOIC	168	37	0
DS2108	B7	MAY '01	26989	0111	ATP (Amkor, PI)	DK101048AAC	SOIC	96	40	1
DS2118M	C1	MAR '02	28821	0143	ATK (Amkor, K)	DN120700ABB	SSOP	168	73	0
DS2175	D1	APR '01	26886	0050	ATP (Amkor, PI)	DK036683ABD	SOIC	96	40	0
DS21S07	C1-	FEB '02	28811	0112	Carsem	DM048483AC	TSSOP	168	34	0
DS2401	C2	MAR '02	28838	0208	Carsem	DM218006AA	SOT23	168	45	0

# RELIABILITY MONITOR

STRESS: 0 HR TEST

CONDITIONS: Connect Cap & Base

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1644	B2	FEB '01	26626	0051 Fastech	300700	Power Cap	2	230	5